



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD30N06S4L-23		<b>Issued</b>		20. July 2018	
<b>MA#</b>				MA000988248					
<b>Package</b>				PG-TO252-3-11		<b>Weight*</b>		370.25 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.858	0.23	0.23	2316	2316	
leadframe	non noble metal	iron	7439-89-6	0.215	0.06		581		
	inorganic material	phosphorus	7723-14-0	0.065	0.02		174		
	non noble metal	copper	7440-50-8	215.017	58.08	58.16	580742	581497	
wire	non noble metal	aluminium	7429-90-5	9.485	2.56	2.56	25618	25618	
encapsulation	organic material	carbon black	1333-86-4	1.203	0.32		3250		
	plastics	epoxy resin	-	21.055	5.69		56867		
	inorganic material	silicondioxide	60676-86-0	98.055	26.48	32.49	264838	324955	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.01	1.01	10102	10102	
plating	non noble metal	nickel	7440-02-0	0.091	0.02		245		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.02	1	246	
solder	noble metal	silver	7440-22-4	0.031	0.01		85		
	non noble metal	tin	7440-31-5	0.025	0.01		68		
	non noble metal	lead	7439-92-1	1.203	0.32	0.34	3249	3402	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		52		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		16		
	non noble metal	copper	7440-50-8	19.177	5.18	5.19	51796	51864	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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